FILING DATE TRANSLATION YES NO

PTO-1449 Application No. Applicant(s) To be Assigned Howard, et al. Docket Number Group Art Unit Filing Date Information Disclosure Citation To be Assigned TI-36332 Sept. 10, 2003 In an Application (032350.B531) **U.S. PATENT DOCUMENTS** DOCUMENT NO. DATE NAME CLASS **SUBCLASS** Α В  $\overline{\mathsf{c}}$ D Ε F G Η I J K L M  $\overline{N}$ FOREIGN PATENT DOCUMENTS DOCUMENT NO. DATE **COUNTRY** CLASS **SUBCLASS** 0 P Q DOCUMENT (Including Author, Title, Source, and Pertinent Pages) DATE "Challenges in High Yield, Fine Pitch Solder Ball Attachment", by Ivy Qin, et al., SEMI - Semicon 05/2001 Singapore Semiconductor Packaging Conference, pp. 1-10 T DATE CONSIDERED EXAMME at I citation considered, whether or not citation is in conformance with MPEP § 609. Draw line through citation If not in conformance and not considered include copy of this form with next communication to the applicant. U.S. PATENT AND TRADEMARK OFFICE